

To our customers,

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## Old Company Name in Catalogs and Other Documents

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Renesas Electronics website: <http://www.renesas.com>

April 1<sup>st</sup>, 2010  
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (<http://www.renesas.com>)

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TRANSCEIVER MODULE  
**NL1100,NL1100L**

**FAST SERIAL INFRARED LINK FOR IrDA**  
**DATA RATE: 2.4 k to 4.0 Mbps**

**DESCRIPTION**

The NL1100 and NL1100L are Infrared Rays link units for high speed application of IrDA. Their units incorporate a high speed infrared Rays LED and an integrated photo detector with wide bandwidth amplifier.

High speed transmission can be obtained at distances of at least 1 meter.

**FEATURES**

- Conform to IrDA Ver. 1.1 standards
- High data rate
 

Channel A:	2.4 k to 115.2 kbps
Channel B:	0.576 M to 4.0 Mbps
- Data link distance            1 cm to 1 m
- Small size (Mold PKG)        6.9 × 13.2 × 6.5 (mm)
- Includes daylight cancellation
- NL1100L : Surface mount type (Optional device : When purchasing this device, contact an NEC sales representative.)

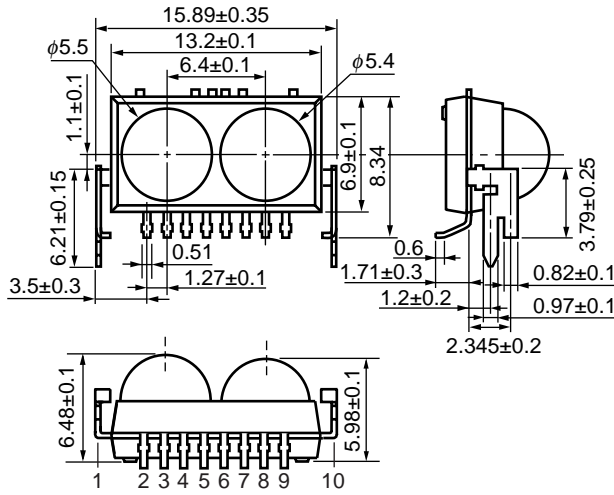
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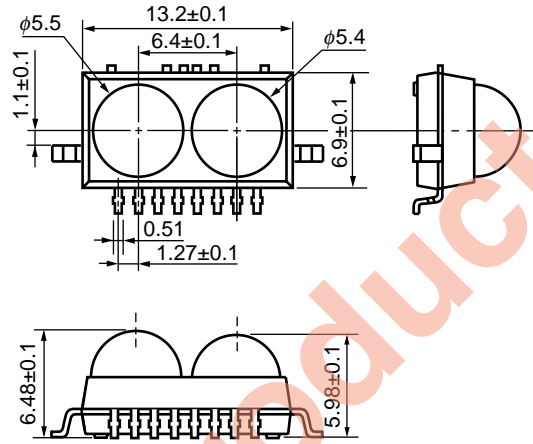
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**PACKAGE DIMENSIONS**  
in millimeters

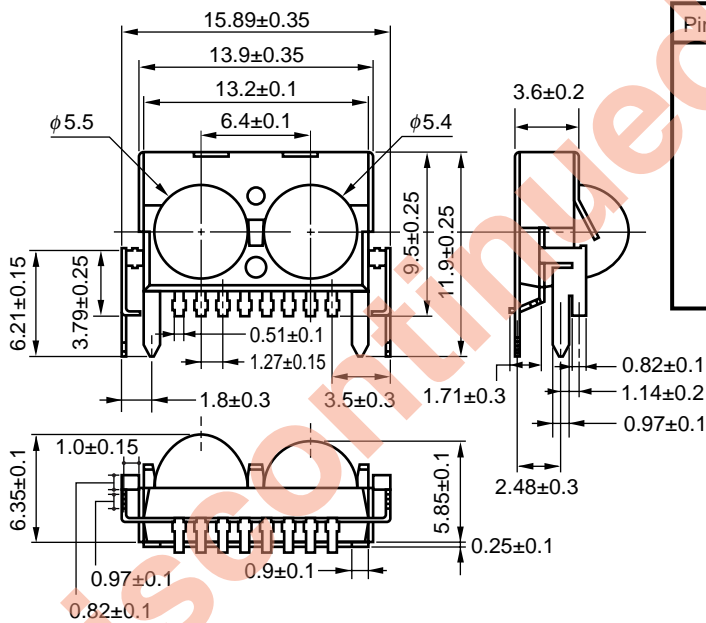
**NL1100**



**NL1100L**



**NL1100-1**



**PIN CONNECTIONS**

Pin No.	Function
1	C1: PIN Bypass Capacitor
2	GND: Ground
3	C6
4	Vcc: Supply Voltage
5	RXD-B: Receiver Data Output Channel B
6	GND: Ground
7	TXD: Transmitter Data Input
8	RXD-A: Receiver Data Output Channel A
9	NC
10	LEDA: LED Anode

★ ORDERING INFORMATION

Part Number	Packages
NL1100	DIP
NL1100-1	DIP with shield case
NL1100L	SMD

ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 °C, unless otherwise specified)

Parameter	Symbol	Conditions	Ratings	Unit
Supply Voltage	V <sub>CC</sub>		-0.5 to +7.0	V
Data Input Voltage	V <sub>TXD</sub>		-0.5 to V <sub>CC</sub> +0.5	V
Data Output Voltage	V <sub>RXD</sub>		-0.5 to V <sub>CC</sub> +0.5	V
Peak LED Current	I <sub>FP</sub>	PW < 1 μs, duty < 1 %	1.0	A
Repetitive Pulse LED Current	I <sub>RP</sub>	PW < 100 μs, duty < 10 %	500	mA
Operating Ambient Temperature	T <sub>A</sub>		0 to +70	°C
Storage Temperature	T <sub>stg</sub>		-25 to +85	°C
★ Lead Soldering Temperature (10 s)	T <sub>slid</sub>		260	°C

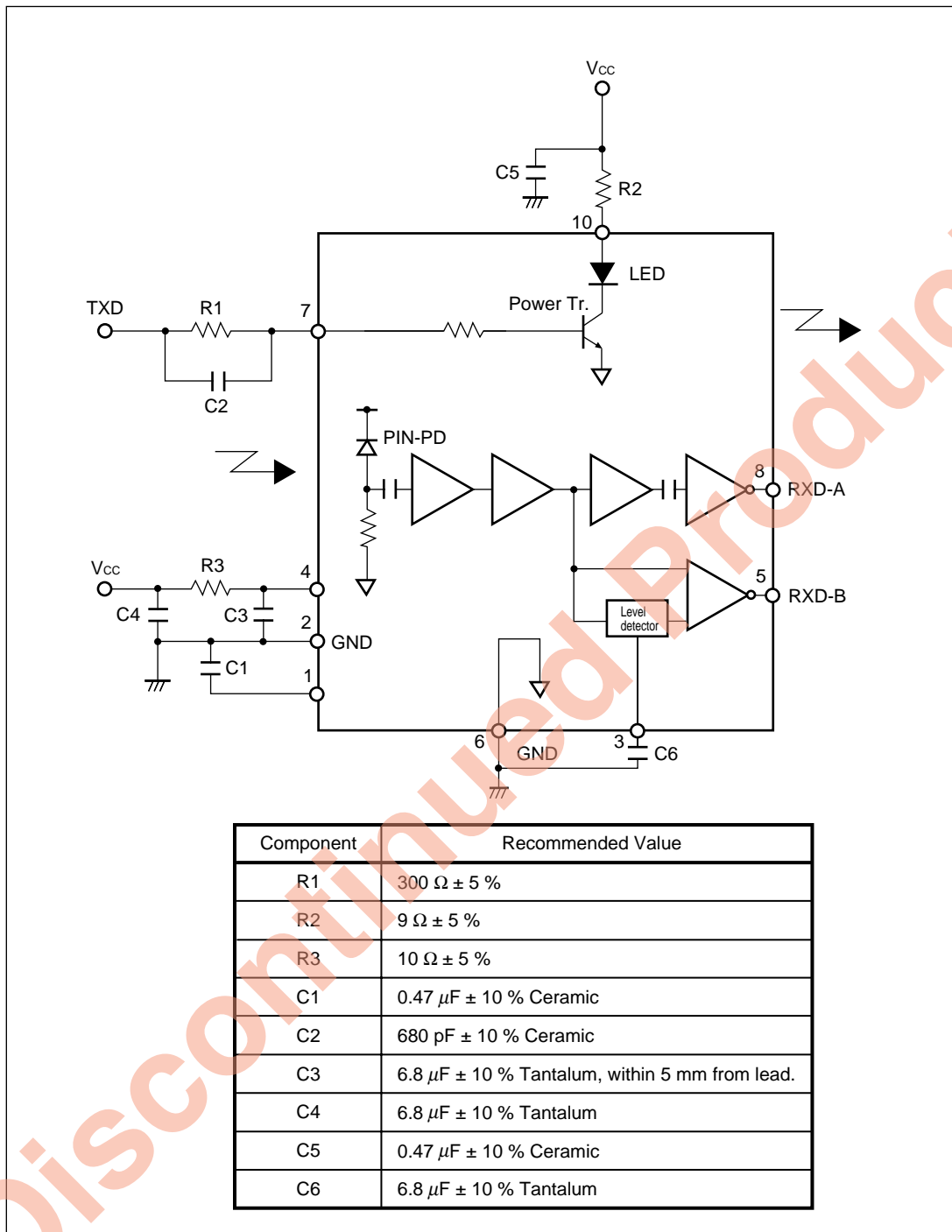
RECOMMENDED OPERATING CONDITIONS (T<sub>A</sub> = 25 °C, unless otherwise specified)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Supply Voltage	V <sub>CC</sub>		4.75	5.0	5.25	V
Data Input Voltage (High)	V <sub>IH</sub>		2.5		5.25	V
Data Input Voltage (Low)	V <sub>IL</sub>		0		0.3	V
Logic High Input Irradiance	E <sub>IH</sub>	2.4 kbps to 115.2 kbps	0.0036		500	mW/cm <sup>2</sup>
		0.576 Mbps to 4.0 Mbps	0.0090		500	
Logic Low Input Irradiance	E <sub>IL</sub>				0.3	μW/cm <sup>2</sup>
Pulse LED Current	I <sub>LED</sub>		250		350	mA
Data Rate (Channel A)			2.4 k		115.2 k	bps
Data Rate (Channel B)			0.576 M		4.0 M	bps

ELECTRO-OPTICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Transmitter	Peak Wavelength	$\lambda_P$	I <sub>F</sub> = 300 mA	850	875	900	nm
	Radiant Intensity (Low)	I <sub>EL</sub>	GND < V <sub>I</sub> < 0.3 V			0.3	mW/sr
	Radiant Intensity (High)	I <sub>EH</sub>	V <sub>I</sub> = 2.5 V	100	160	300	mW/sr
	Viewing Angle	$\theta$	I <sub>F</sub> = 300 mA	30		60	deg.
	LED Pulse Forward Voltage	V <sub>FP</sub>	I <sub>F</sub> = 300 mA		2.0	2.5	V
	Data Input Current (Low)	I <sub>IL</sub>	GND < V <sub>I</sub> < 0.3 V	-1.0	0	1.0	$\mu$ A
	Data Input Current (High)	I <sub>IH</sub>	V <sub>I</sub> = 2.5 V, R <sub>I</sub> = 300 $\Omega$		5.0		mA
	LED Leakage Current	I <sub>LK</sub>	V <sub>CC</sub> = 5.25 V, GND < V <sub>I</sub> < 0.3 V			100	$\mu$ A
	Rise Time	t <sub>r</sub>	V <sub>I</sub> = 2.5 V, t <sub>pw</sub> (TXD) = 125 ns,			40	ns
	Fall Time	t <sub>f</sub>	f = 2.0MHz			40	ns
	Pulse Width	t <sub>pw</sub>		115	125	135	ns
Receiver	Data Output Voltage (Low)	V <sub>OL</sub>	RXD-A		0.04	0.4	V
			RXD-B		0.15	0.4	
	Data Output Voltage (High)	V <sub>OH</sub>	RXD-A, RXD-B	V <sub>CC</sub> -0.5	V <sub>CC</sub> -0.1		V
	Pulse width @9.6 kbps			1.0		20	$\mu$ s
	Pulse width @115.2 kbps			1.0		2.3	$\mu$ s
	Pulse width @1.152 Mbps			200		500	ns
	Pulse width @4.0 Mbps					175	ns
	Viewing Angle	$\theta$		30	45		deg.
	Circuit Current	I <sub>CC</sub>	GND < V <sub>I</sub> < 0.3 V		4.0		mA
V <sub>I</sub> = 2.5 V					20		

RECOMMENDED CIRCUIT (LED drive current: 300 mA)



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★ **RECOMMENDED SOLDERING CONDITIONS**

**(1) Soldering by soldering iron**

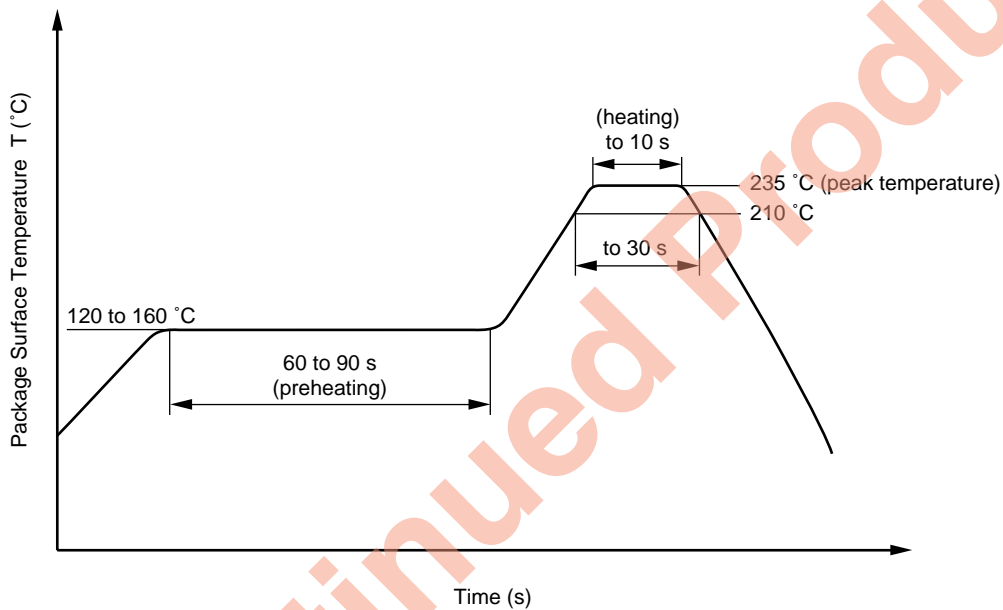
Leave 1.5 to 2.0 mm from the lead root of an optical semiconductor device.

- Temperature            260 °C or below
- Time                      10 seconds or less

**(2) Infrared reflow soldering**

- Number of reflows        Two
- Storage conditions        25 °C , 60 % RH, After opening the dry pack, please use within 48 hours. If the term of storage have expired, please baking 10 hours at 100 °C.

Recommended Temperature Profile of Infrared Reflow



**(3) Dip soldering**

- Temperature            260 °C or below (molten solder temperature)
- Time                      10 seconds or less
- Number of times        One



[MEMO]

Discontinued Product

**CAUTION**

**Within this device there exists GaAs (Gallium Arsenide) material which is a harmful substance if ingested. Please do not under any circumstances break the hermetic seal.**

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